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COMPOSITION FOR ELECTROPLATING PALLADIUM ALLOYS AND
ELECTROPLATING PROCESS USING THAT COMPOSITION

ABSTRACT

5 An aqueous electroplating bath for the electrodeposition of palladium alloys in a mixed ligand system. A first ligand operates to form a complex of palladium and a second ligand functions to form a complex of another metal which brings the plating potentials of the two metals closer together. Palladium and the alloying metal thus exist as complexes with different structures.